

**DIE ATTACH MATERIAL FOR TBGA OR FLEXIBLE CIRCUITRY**

Abstract of the Disclosure

An attachment material is provided between the die and the solder balls of a  
5 TBGA or other flexible circuitry package that is sufficiently compliant to absorb  
pressure between the two, so as not to apply stress to the solder balls. The attachment  
material is also sufficiently rigid, with a low coefficient of thermal expansion (CTE), so  
that the material does not excessively expand and contract during thermal cycling  
relative to the die. More preferably, the attachment material has a CTE close to that of  
10 the die to prevent breakage of the tape at the junction between the tape and the die.

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